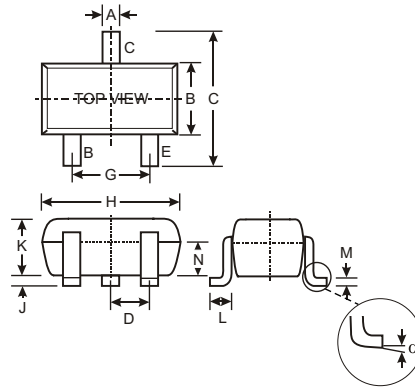


Features

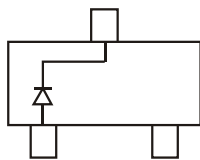
- Low Forward Voltage Drop
- Guard Ring Die Construction for Transient Protection
- Ideal for low logic level applications
- Low Capacitance
- Also Available in Lead Free Version

Mechanical Data

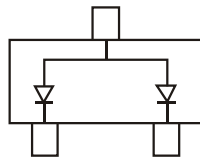
- Case: SOT-523, Molded Plastic
- Case Material UL Flammability Rating: 94V-0
- Moisture sensitivity: Level 1 per J-STD-020A
- Terminals: Solderable per MIL-STD-202, Method 208
- Also Available in Lead Free Plating (Matte Tin Finish). Please see Ordering Information, Note 4, on Page 3
- Polarity: See Diagrams Below
- Marking: See Diagrams Below & Page 3
- Weight: 0.002 grams (approx.)
- Ordering Information, see Page 3



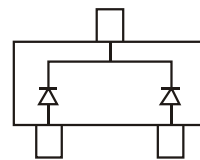
SOT-523			
Dim	Min	Max	Typ
A	0.15	0.30	0.22
B	0.75	0.85	0.80
C	1.45	1.75	1.60
D	—	—	0.50
G	0.90	1.10	1.00
H	1.50	1.70	1.60
J	0.00	0.10	0.05
K	0.60	0.80	0.75
L	0.10	0.30	0.22
M	0.10	0.20	0.12
N	0.45	0.65	0.50
α	0°	8°	—
All Dimensions in mm			



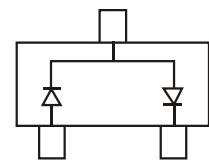
SDMP0340LT Marking: SM



SDMP0340LAT Marking: SQ



SDMP0340LCT Marking: SP



SDMP0340LST Marking: SN

Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	40	V
Working Peak Reverse Voltage	V_{RWM}		
DC Blocking Voltage	V_R		
RMS Reverse Voltage	$V_{R(RMS)}$	28	V
Forward Continuous Current (Note 1)	I_{FM}	30	mA
Non-Repetitive Peak Forward Surge Current @ 8.3ms Single half sine-wave superimposed on rated load (JEDEC method)	I_{FSM}	200	mA
Power Dissipation (Note 1)	P_d	150	mW
Thermal Resistance, Junction to Ambient (Note 1)	$R_{\theta JA}$	833	$^\circ\text{C}/\text{W}$
Operating and Storage Temperature Range	T_j, T_{STG}	-40 to +125	$^\circ\text{C}$

Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 2)	$V_{(BR)R}$	40	—	—	V	$I_R = 10\mu\text{A}$
Forward Voltage Drop (Note 2)	V_F	—	290	370	mV	$I_F = 1\text{mA}$
Leakage Current (Note 2)	I_R	—	—	1.0	μA	$V_R = 10\text{V}$
Total Capacitance	C_T	—	2	—	pF	$V_R = 1\text{V}, f = 1.0\text{MHz}$

- Notes: 1. Device mounted on FR-4 PC board with recommended pad layout, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
 2. Short duration test pulse used to minimize self-heating effect.

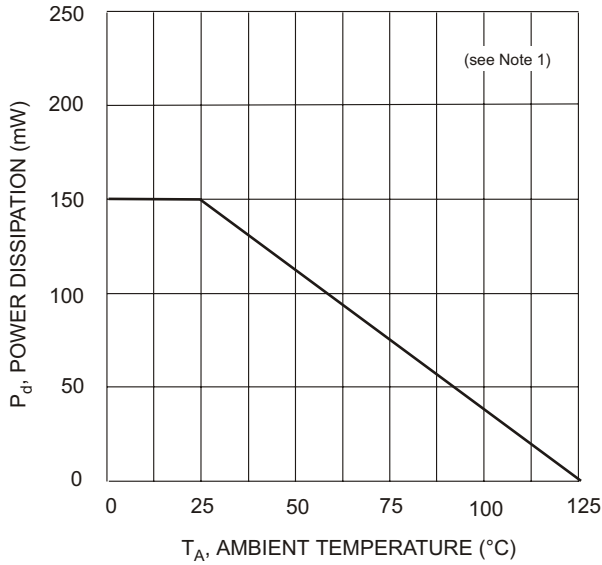


Fig. 1, Power Derating Curve

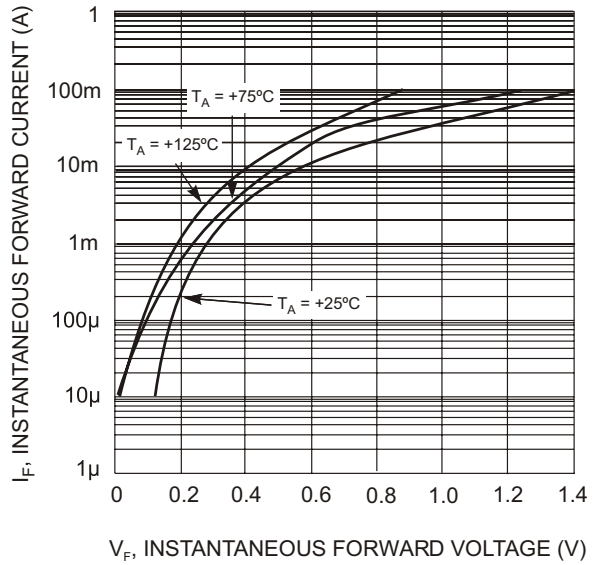


Fig. 2, Typical Forward Characteristics

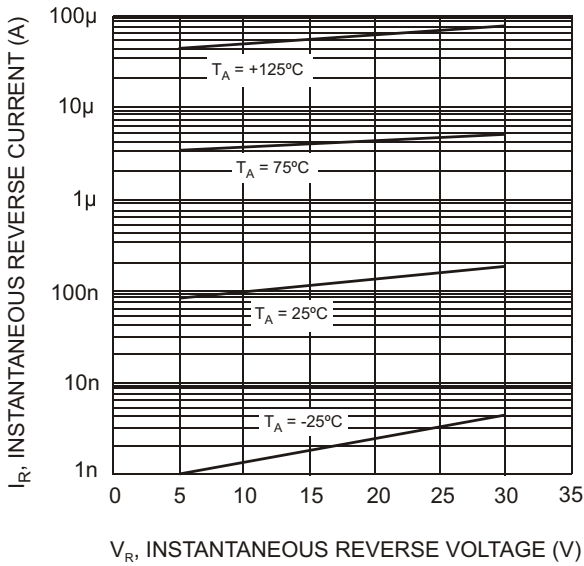


Fig. 3, Typical Reverse Characteristics

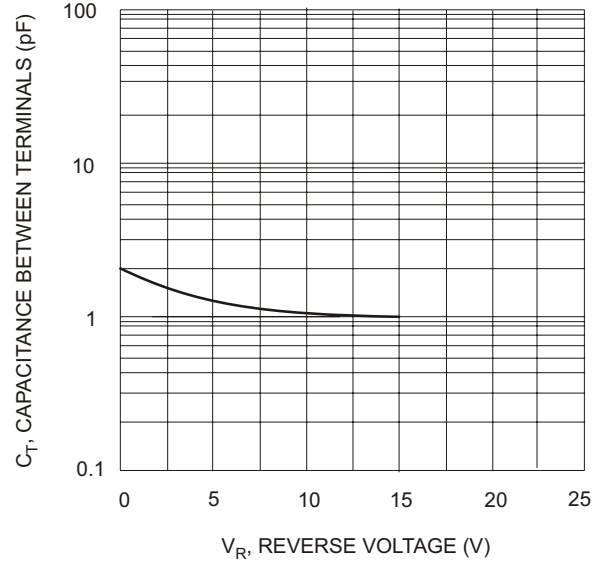


Fig. 4, Typical Capacitance Between Terminals Characteristics

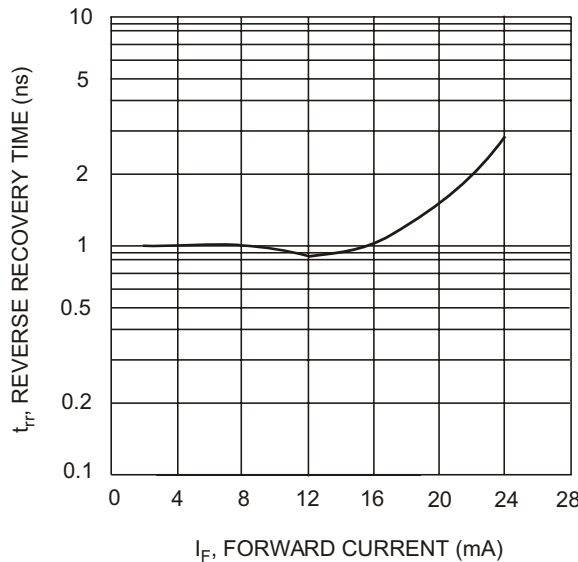
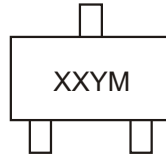


Fig. 5, Typical Reverse Recovery Time Characteristics

Ordering Information (Note 3)

Device	Packaging	Shipping
SDMP0340LT-7	SOT-523	3000/Tape & Reel
SDMP0340LST-7	SOT-523	3000/Tape & Reel
SDMP0340LCT-7	SOT-523	3000/Tape & Reel
SDMP0340LAT-7	SOT-523	3000/Tape & Reel

- Notes:
- For Packaging Details: go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.
 - For Lead Free version (with Lead Free terminal finish) part number, please add "-F" suffix to part number above.
Example: SDMP0340LAT-7-F.

Marking Information


XX = Product Type Marking Code (See Page 1)
 YM = Date Code Marking
 Y = Year (ex: N = 2002)
 M = Month (ex: 9 = September)

Date Code Key

Year	2001	2002	2003	2004	2005	2006	2007	2008	2009
Code	M	N	P	R	S	T	U	V	W

Month	Jan	Feb	March	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D